

Customer No.: 31561
Application No.: 10/707,825
Docket No.: 10786-US-PA

AMENDMENT

Please amend the application as indicated hereafter.

To the Claims :

1. (original) A flip-chip gold bump structure formed on a wafer, comprising:
at least one gold bump;
a nickel layer on the gold bump; and
a copper layer on the nickel layer.
2. (original) The flip-chip gold bump structure of claim 1, wherein the nickel layer has a thickness about from 0.1 μm to about 20 μm .
3. (original) The flip-chip gold bump structure of claim 1, wherein the copper layer has a thickness about from 0.1 μm to about 10 μm .
4. (original) The flip-chip gold bump structure of claim 1, wherein the gold bump has a height about from 3 μm to about 150 μm .
5. (original) A flip-chip package structure adapted to connect a chip and a chip substrate, comprising:
at least one gold bump on the chip;
a nickel layer on the gold bump; and
a solder containing copper on the nickel layer for connecting the chip and the chip substrate.

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6. (original) The flip-chip package structure of claim 5, wherein the solder containing copper includes a solder alloy.
7. (original) The flip-chip package structure of claim 6, wherein copper in the solder alloy is from about 0.7 wt.% to about 3.0 wt.%.
8. (original) The flip-chip package structure of claim 5, wherein the nickel layer has a thickness about from 0.1 μm to about 20 μm .
9. (original) The flip-chip package structure of claim 5, wherein the gold bump has a height about from 3 μm to about 150 μm .
10. (cancelled)
11. (cancelled)
12. (cancelled)
13. (cancelled)
14. (cancelled)
15. (cancelled)
16. (cancelled)
17. (cancelled)
18. (cancelled)
19. (cancelled)
20. (cancelled)
21. (cancelled)
22. (cancelled)

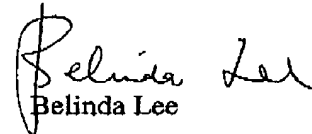
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CONCLUSION

Pursuant to Examiner's instruction, a complete listing of all the claims is now presented. If the Examiner believes that a conference would be of value in expediting the prosecution of this application, he is cordially invited to telephone the undersigned counsel to arrange for such a conference.

Date : *Dec. 7, 2005*

Respectfully submitted,


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